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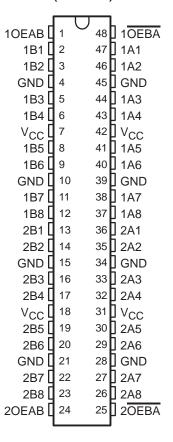
- Members of the Texas Instruments Widebus™ Family
- Inputs are TTL-Voltage Compatible
- Flow-Through Architecture Optimizes
 PCB Layout
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- EPIC[™] (Enhanced-Performance Implanted CMOS) 1-µm Process
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings

description

The 'ACT16623 are 16-bit transceivers designed for asynchronous two-way communication between data buses. The control-function implementation allows for maximum flexibility in timing.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the output-enable (OEBA and OEAB) inputs. The output-enable inputs can be used to disable the device so that the buses are effectively isolated.

54ACT16623 . . . WD PACKAGE 75ACT16623 . . . DL PACKAGE (TOP VIEW)



The dual-enable configuration gives the bus transceiver the capability to store data by simultaneously enabling OEBA and OEAB. Each output reinforces its input in this transceiver configuration. When both control inputs are enabled and all other data sources to the two sets of bus lines are at high impedance, the bus lines remain at their last states.

The 74ACT16623 is packaged in TI's shrink small-outline package, which provides twice the functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16623 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74ACT16623 is characterized for operation from –40°C to 85°C.



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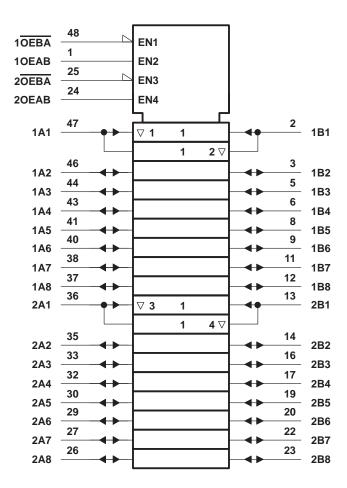


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FUNCTION TABLE (each 8-bit section)

INP	UTS	OPERATION
OEBA	OEAB	OPERATION
L	L	B data to A bus
Н	Н	A data to B bus
Н	L	Isolation
L	Н	B data to A bus, A data to B bus

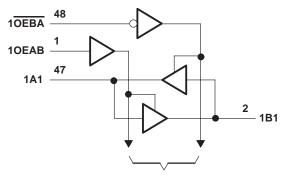
logic symbol†

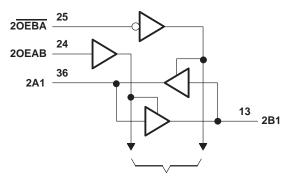


[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)





To Seven Other Channels

To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)($0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, V _O (see Note 1)($0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V _{CC} or GND	±400 mA
Maximum power package dissipation at T _A = 55°C (in still air) (see Note 2): DL package	1.2 W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

		54	ACT1662	23	74	ACT1662	23	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage (see Note 4)	4.5	5	5.5	4.5	5	5.5	V
VIH High-level input voltage		2		CN	2			V
V _{IL}	Low-level input voltage		FL	0.8			0.8	V
٧ _I	Input voltage	0	,Q	Vcc	0		VCC	V
VO	Output voltage	0	Ç	VCC	0		VCC	V
ЮН	High-level output current	4	,	-24			-24	mA
loL	Low-level output current	07		24			24	mA
Δt/Δν	Input transition rise or fall rate	0		10	0		10	ns/V
TA	Operating free-air temperature	-55		125	-40		85	°C

NOTES: 3. Unused inputs should be connected to V_{CC} through a pullup resistor of approximately 5 $k\Omega$ or greater.

4. All V_{CC} and GND pins must be connected to the proper power supply.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAI	RAMETER	TEST CONDITIONS	V	T,	Δ = 25°C		54ACT	16623	74ACT	16623	UNIT
PAI	RAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
		Jour - 50 uA	4.5 V	4.4			4.4		4.4		
		I _{OH} = -50 μA	5.5 V	5.4			5.4		5.4		
Vон		1011 - 24 mA	4.5 V	3.94			3.8		3.8		V
		I _{OH} = -24 mA	5.5 V	4.94			4.8		4.8		
		I _{OH} = -75 mA [†]	5.5 V				3.85	4	3.85		
		lo 50 uA	4.5 V			0.1		0/1		0.1	
		I _{OL} = 50 μA	5.5 V			0.1		0.1		0.1	V
VOL		la 24 mA	4.5 V			0.36	1	0.44		0.44	
		I _{OL} = 24 mA	5.5 V			0.36	5	0.44		0.44	
		I _{OL} = 75 mA [†]	5.5 V				Q ₀	1.65		1.65	
II	Control inputs	V _I = V _{CC} or GND	5.5 V			±0.1	Ya	±1		±1	μΑ
loz	A or B ports	V _O = V _{CC} or GND	5.5 V			±0.5		±5		±5	μΑ
Icc		$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80		80	μΑ
ΔI _{CC} ‡		One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			0.9		1		1	mA
Ci	Control inputs	V _I = V _{CC} or GND	5 V		4.5						pF
C _{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		16						pF

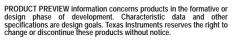
T Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	T,	չ = 25°C	;	54ACT	16623	74ACT	16623	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
t _{PLH}	A or B	B or A	4.2	7.3	9.5	4.2	10.4	4.2	10.4	ns
t _{PHL}	AOIB	BOIA	3.1	7.3	9.5	3.1	10.3	3.1	10.3	115
^t PZH	OEDA.	А	2.7	6.8	8.8	2.7	9.5	2.7	9.5	ns
tpZL	OEBA	A	3.5	8.2	10.2	3.5	11.1	3.5	11.1	113
^t PHZ	OEDA	А	6	9.6	11.3	6	12	6	12	ns
t _{PLZ}	OEBA	A	5.3	8.6	10.3	5.3	10.7	5.3	10.7	115
^t PZH	OEAB	В	4.1	6.9	8.7	4.1	9.3	4.1	9.3	nc
^t PZL	OLAB	В	5.1	7.9	9.7	5.1	10.6	5.1	10.6	ns
^t PHZ	OEAB	В	5.1	8.2	10.2	5.1	10.4	5.1	10.4	ns
^t PLZ	OLAB	5	4.4	7.4	9.3	4.4	9.5	4.4	9.5	113

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CO	TYP	UNIT		
C .	Dower discination conscitance per transceiver	Outputs enabled	C 50 pE	f = 1 MHz	56	nE
Cpd	Power dissipation capacitance per transceiver	Outputs disabled	C _L = 50 pF,	t = 1 MHz	11	pF

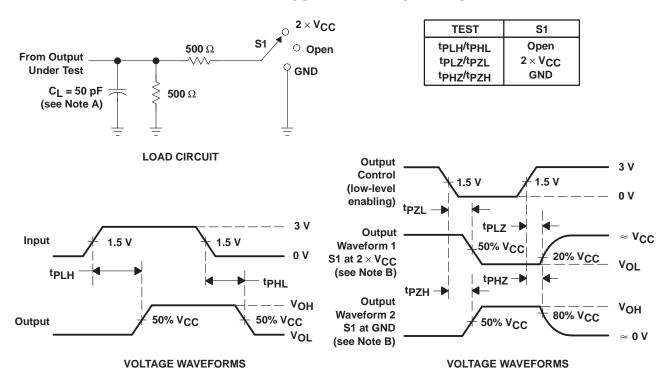




[‡] For I/O ports, the parameter IOZ includes the input leakage current.

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_f = 3 \ ns$, $t_f = 3 \ ns$.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ACT16623DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16623DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16623DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16623DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT16623DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1





*All dimensions are nominal

I	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
I	74ACT16623DLR	SSOP	DL	48	1000	346.0	346.0	49.0

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